

**Indian Institute of Information Technology,
Design and Manufacturing, Kurnool
Jagannathagattu, Dinidevarapadu, Kurnool.**



Tender Document

For

Supply and Installation of NILAB VIEW

Date: 18.April 2019

Item	:	Supply and Installation of NILABVIEW, Multisim and DAQ Cards (Specification Enclosed as Annexure)
Tender Enquiry No	:	IIITKL/19-20/S&P/NILABVIEW/02 Dt. 18 .April.2019
EMD	:	Earnest Money Deposit (EMD) for Rs. 48,000/- (Rupees Forty Eight Thousand Only) in the form of Demand Draft/Bankers Cheque/Bank guarantee drawn in favor of "The Registrar , "IIITD&M Kurnool" payable at Kurnool.
Submission of Offer	:	Two Bid System: Two bid system will be followed in this tender. In this system the bidder must submit his offer in two separate sealed envelopes . Both the technical bid and commercial bid envelopes should be securely sealed and stamped separately and clearly marked as "Envelope No: 1 – Technical Bid" and "Envelope No: 2 – Commercial Bid" respectively. EMD should be placed in the Technical Bid. This two separate sealed envelopes should be placed in single envelope super scribing the tender No and description of the item.
Place of Submission Bid	:	The Registrar Indian Institute of Information Technology, Design and Manufacturing Kurnool Jagnnathagattu, Dinnidevarapadu, Kurnool, Andhrapradesh-518007.
Due Date (For submission of bids)	:	02.00 PM 20.05.2019 (any bid received after the due date and time by any means will be summarily rejected)
Opening of Technical Bid	:	04:00 PM, 20.05.2019
Delivery Period	:	04 weeks from the date of Purchase Order

Important :

All communications are to be addressed to in the name of Registrar, IIITD&M Kurnool only and not in the name of any officer and mails has to be sent to official purchase email id purchase@iiitk.ac.in

Terms and Conditions

1. The Bidders are requested to give detailed tender in two bid format.

Envelope-I : **Technical Bid**
Envelope-II : **Commercial Bid**

2. The bidder has to accept all terms and conditions of the Institute and conditional offers will not be accepted.

3. The tender document can be downloaded from the IIITDM Kurnool website www.iiitdmkl.ac.in at free of cost. The duly filled tenders should be submitted to The Registrar, Indian Institute of Information Technology, Design and Manufacturing, Kurnool, Jagannathagattu, Dinnidevarapadu, Kurnool -518007 **on or before due date 02.00 PM, 20.05.2019**. Extension of due date will not be entertained.

4. Tenders which are submitted without following the two bid offer system will summarily be rejected.

5. **Envelope No-1 : Technical Bid**

- i) EMD for Rs.48,000 /- (Rupees Forty Eight thousand only) in the form of Demand Draft/ Bankers Cheque / Bank guarantee drawn in favor of “The Registrar, **IIITD&M Kurnool**” **payable at Kurnool**. (The EMD without interest shall be returned to the unsuccessful bidders after finalization of the tender).
- ii) The firms registered and having valid NSIC Certificate are exempt from submission of EMD.
- iii) The leaflet / catalogue of the product quoted.
- iv) **The OEM certificate or the valid authorization letter from the OEM for sale & support of the product quoted.**
- v) The copies of purchase orders received from Industry / Educational / Research Institution etc.
- vi) Bids should have a validity of **90 days**.
- vii) The technical offer **should not contain any price information**.
- viii) The tenders not meeting the eligibility criteria will be similarly rejected. Hence the tenderers are advised to attach relevant documents in support of their eligibility

6. **Envelope No-2 : Commercial Bid**

This should contain only the price information along with commercial terms and conditions.

7. AMC Support/Training

- i) **The Bidder shall provide one year free AMC support.**
- ii) The bidder shall also arrange to provide free installation of the software if there is change in the licensed server.
- iii) The bidder shall arrange to provide free training to our faculty/student at the institute for a minimum duration of three days.

8. Opening of Technical Bids

The technical bids will be opened on the scheduled date in the presence of the bidders or their authorized representatives who choose to attend the technical bid opening.

9. Technical Evaluation

- i) All the technical aspects of the bids received will be evaluated for suitability and specification. If required, the Institute may seek additional clarification from the bidders.
- ii) The technical recommendation shall be final and binding on all the parties.
- iii) The technically qualified firms will be intimated about Price Bid opening by email.

10. Opening of Commercial Bids

IIITD&M Kurnool will open commercial bids of only the shortlisted bidders in technical evaluation in the presence of the bidders or their authorized representatives who choose to attend the commercial bid opening. The representatives of shortlisted firms only will be allowed for commercial bid opening.

11. Delivery Period / Timelines

The deliveries and installation must be completed **within 04 weeks** from the date of purchase order.

12. Locations for the supply / services

The bidders may note that the items covered by this document is required to be supplied and installed at

**IIITDM Kurnool,
Jagannathagattu,
Near Pullareddy Engineering College
Dinnedevarapadu village,
Kurnool, Kurnool District
Andhra Pradesh-518007.**

13. Price

- i) **The price should be quoted in INR only. GST payable extra.**

- ii) **The price quoted shall be for supply, delivery and Installation at specified room of IIITDM KURNOOL, Kurnool District, and Andhra Pradesh.**
- iii) The packing, forwarding, freight, insurance and commissioning charges, if any extra may be quoted separately in commercial bid.

14. Installation

- i) Bidder shall be responsible for installation as applicable and for after sales service during the warranty and thereafter.
- ii) Installation to be arranged by the supplier free of cost and the same is to be done within 15 days of the arrival of the item at site.

15. Indemnity

The vendor shall indemnify, protect and save IIITDM Kurnool against all claims, losses, costs, damages, expenses, action suits and other proceeding, resulting from infringement of any law pertaining to patent, trademarks, copyrights etc., or such other statutory infringements in respect of all the items supplied by them.

16. Freight and Insurance

The items to be supplied will be insured by the vendor at his cost against all risks of loss or damage from the date of shipment till such time it is delivered at IIITDM Kurnool, Kurnool District, and Andhra Pradesh.

17. Payment

100% payment after delivery, and acceptance by IIITDM on submission of Bank Guarantee for an equivalent value of 10% of PO value valid till warranty period plus 2 months.

The bidders may note that **other modes of payment like advance payment and payment against delivery is not considered.**

18. Penalty for delayed services / LD

- i) As time is the essence of the contract, delivery period mentioned in the purchase order should be strictly adhered to. Otherwise the LD clause will be applied / enforced.
- ii) If the supplier fails to supply, and fix the item as per specifications mentioned in the order within the due date, the supplier is liable to pay liquidated damages of 1% of order value for delay of every week or or part thereof subject to a maximum of 10% beyond the due date. Such money will be deducted from any amount due or which may become due to the supplier.
- iii) IIITD&M Kurnool reserves the right to cancel the order in case the delay is more than 04 weeks and the contractor is not eligible for any damage from the Institute and contractor will forfeit his claim for EMD.

19. Jurisdiction

The disputes, legal matters, court matters, if any, shall be subject to Courts in the district of Kurnool Jurisdiction only.

20. Force Majeure

- a) IIITDM Kurnool may consider relaxing the penalty and delivery requirements, as specified in this document, if and to the extent that the delay, in performance or other failure to perform its obligations under the contract, is the result of a force majeure.
- b) If the due date of submission of tender / tender opening is declared a holiday for the Institute, the due date for submission of tender / tender will be extended to same time on next working day.

21. Arbitration

All disputes of any kind arising out of supply, commissioning, acceptance, warranty maintenance etc., shall be referred by either party (IIITDM Kurnool or the bidder) after issuance of 30 days' notice in writing to the other party clearly mentioning the nature of dispute and will be referred to the arbitrator to be nominated by The Registrar, IIITDM Kurnool. The Venue for arbitration shall be Chennai / Hyderabad, India.

22. Acceptance of the terms and conditions of tender document

The bidders has to accept all the terms and conditions of this tender document and it is made known that the bidders quoting for this tender had impliedly accepted the terms and conditions of this tender.

23. Interpretation of the clauses in the Tender Document

In case of any ambiguity / dispute in the interpretation of any of the clause in this tender document, interpretation of The Registrar, IIITD&M Kurnool shall be final and binding on all parties. The IIITD&M Kurnool reserves the right to accept the offer in full or in parts or reject the offer summarily or partly without assigning any reasons.

Sd/-

**कुलसचिव / Registrar
IIITD&M KURNOOL**

Technical Specification

Annexure-I

Supply and Installation of NILAB VIEW AND MULTISIM

Technical Specification of NI Multisim Circuit Simulation Software

NI Multisim circuit Simulation Software for Analog, Digital and Power electronics Lab- 25 users –Perpetual License with three years of SSP-1 No

Description of the Item	Quantity	Price
Multisim integrates industry standard SPICE simulation with an interactive schematic environment to instantly visualize and analyze electronic circuit behavior. Multisim has an intuitive interface that helps educators reinforce circuit theory and improve retention of theory throughout engineering curriculum. Researchers and designers use Multisim to reduce PCB prototype iterations and save development costs by adding powerful circuit simulation and analyses to the design flow.	1 No	
Ability to perform system design and circuits teaching with the addition of new SPICE models, interface with Industry standard hardware connectors		
More than 12,000 components and simulation models including basic, advanced analog and digital parts		
Powerful insight into circuit behavior with Monte Carlo and 14 other advanced analysis		
Fully mixed mode A/D simulation		
Standard SPICE 3F5/XSPICE support		
Virtual, interactive and animated components		
• Measurement probes		
Components and Circuits wizard capabilities		
RF design kit		
Ladder diagrams		
22 Virtual Instruments such as Oscilloscope, Logic analyzers to visualize simulation		
PLD schematic environment for logic gates, encoders, decoders, adders, shift registers and counters etc to generate VHDL , programming files, and deploy logic to a Xilinx FPGA completes the sequences.		
Micro controller simulation		

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| <ul style="list-style-type: none">• Model makers capability• LabVIEW Multisim co-simulation• Virtual NI ELVIS I and II and NI MyDAQ functionality• NI LabVIEW Vis as instruments and sources Interface with microphones and speakers• Export to Mentor PADS layout• Cadence PSpice model simulation support• PLD/VHDL output capability• Spreadsheet view• Multisim snippets• Xilinx tools supported• Digital Signal Analysis• Ability to configure pin and gate swapping• Display of net/component attributes in status bar• • Power electronic tools capabilities like parameterizable machines, transistors, thyristors, voltage controlled switches, PWM generators and Phase angle controllers etc | | |
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Technical Specification of NILAB VIEW

NI LabVIEW Professional Development Software for Academic Teaching purpose only – 25 users – Perpetual license with three year of SSP Training: 3 days

NI Academic Site License: LabVIEW

LabVIEW

Product	Version
LabVIEW Professional Development System ^{1,2}	2018 SP1 or latest version
LabVIEW NXG	3.0
LabVIEW NXG Web Module	
1 Available for OS X 2 Available for Linux	

LabVIEW for Design

Product	Version
LabVIEW Control Design and Simulation Module	2018 or latest version
LabVIEW Digital Filter Design Toolkit	2018 or latest version
1 Available for OS X 2 Available for Linux	

LabVIEW for Deployment

Product	Version
LabVIEW Real-Time Module	2018 SP1 or latest version
LabVIEW FPGA Module	2018 or latest version
LabVIEW FPGA Xilinx Compilation Tools	ISE 14.7 for LabVIEW 2018
LabVIEW myRIO Toolkit	Vivado 2017.2 for LabVIEW 2018
Automotive Diagnostic Command Set	2018
	18.0
LabVIEW Module for LEGO® MINDSTORMS® ¹	2016 or latest version
Not included on the media. To obtain this software, visit ni.com/downloads .	

LabVIEW for Interface

Product	Version
LabVIEW Data logging and Supervisory Control (DSC) Module	2018 or latest version
NI Vision Development Module	2018 SP1 or latest version
LabVIEW OPC UA Toolkit 2018	2018 or latest version
ECU Measurement and Calibration Toolkit	18.0 or latest version

LabVIEW for Analyze

Product	Version
LabVIEW Sound and Vibration Measurement Suite	2018 or latest version
LabVIEW Advanced Signal Processing Toolkit 2018	2018 or latest version
LabVIEW Electrical Power Toolkit 2018	2018 or latest version
LabVIEW DataFinder Toolkit 2018	2018 or latest version

LabVIEW for Validate

Product	Version
LabVIEW Unit Test Framework Toolkit	2018 or latest version
LabVIEW VI Analyzer Toolkit ^{1,2}	2018 or latest version
LabVIEW Desktop Execution Trace Toolkit	2018 or latest version
1 Available for OS X 2 Available for Linux	2018 or latest version

LabVIEW for Communications

Product	Version
LabVIEW Communications System Design Suite	2.1 or latest version
LabVIEW FPGA Compile Farm Toolkit	18.0 or latest version
Xilinx Compilation Tools for Windows	Vivado 2014.4 for LabVIEW Communications 2.0 or latest version

Test Stand

Product	Version
TestStand	2017 or latest version

LabWindows/CVI

Product	Version
NI LabWindows/CVI Full Development System	2017 or latest version
LabWindows/CVI Execution Profiler	1.0 or latest version
LabWindows/CVI PID Toolkit	2.1 or latest version
LabWindows/CVI Real-Time Module	2017 or latest version
Lab Windows/CVI Signal Processing Toolkit	7.0.2 or latest version
LabWindows/CVI SQL Toolkit	2.3 or latest version

Measurement Studio

Product	Version
Measurement Studio Enterprise Edition	2015 or latest version

VS2010/2012/2013	
Measurement Studio Installer Builder	2015 or latest version

DIAdem

Product	Version
NI DIAdem Professional	2018 or latest version

Stand-Alone Vision Software

Product	Version
Vision Builder for Automated Inspection	2018 or latest version

NI Device Drivers

The following National Instruments device drivers are included with both Academic Site License options. To download any of the device drivers, go to ni.com/downloads/drivers

Product	Version
NI System Configuration	18.0 or latest version
NI-488.2	17.6 or latest version
NI-DAQmx1	18.0 or latest version
NI-DCPower1	18.0 or latest version
NI-DMM1	18.0 or latest version
NI-FGEN1	18.0 or latest version
NI-HSDIO	18.0 or latest version
NI-Motion	18.0 or latest version
NI-SCOPE1	18.0 or latest version
NI-Serial1	17.5.0 or latest version
NI-SWITCH1	18.0 or latest version
NI-Sync 18.0 NI-Time Sync	18.0 or latest version
NI-VISA1	18.0 or latest version
NI-XNET	18.0 or latest version
PXI Platform Services	18.0 or latest version
NI R Series Multifunction RIO Device Drivers	May 2018
FlexRIO Support	18.0 or latest version
Industrial Controller Device Drivers	18.0 or latest version
NI CompactRIO Device Drivers	May 2018
IVI Compliance Package1	18.0 or latest version
Vision Acquisition Software	18.0 or latest version
NI General Security Patch	Q2 2013 or latest version
NI ELVISmx	18.0 or latest version
Includes support for LabVIEW NXG.	

DOWNLOAD SOFTWARE ONLY	
Electric Motor Simulation Kit	2016 or latest version
FlexLogger	2018 R4 or latest version
LabVIEW Analytics and Machine Learning Toolkit	2017 or latest version
LabVIEW MathScript RT Module	2018 or latest version
LabVIEW Model Interface Toolkit	2018 SP1 or latest version
LabVIEW Modulation Toolkit	18.0 or latest version
LabVIEW Robotics Module	2018 or latest version
LabVIEW Softmotion Module	18.0.0 or latest version
LabVIEW State chart Module	2018 or latest version
NI Signal Express	2015 or latest version
VI Package Manager	2018 or latest version
Veristand	2018 SP1 or latest version

Technical Specification for NI-DAQ Card

S.No	Name of the Item	Quantity	Price
1	USB-6003 16-Bit 100 kS/s Multifunction I/O and NI-DAQmx	6No	
2	PCI-6251 (16 AI, 24 DIO, 2 AO, 1.25MS/s) with SCB-68A Noise Rejecting, Shielded I/O Connector Block and SHC68-68-EPM Shielded Cable, 68-D-Type to 68 VHDCI Offset, 2 m	1No	